OSRAM LE T Q8WP **Datasheet**

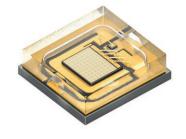




OSRAM OSTAR® Projection Compact

LE T Q8WP

Compact light source in SMT technology, glass window on top, RoHS compliant









Applications

- Entertainment
- Projection & Display

- Visualization

Features

- Package: compact lightsource in SMT technology with glass window on top
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ_{dom} = 530 nm (• true green)
- Corrosion Robustness Class: 3B
- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101-REV-C, Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)



Ordering	Information
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Туре	Luminous Flux ¹⁾ $I_F = 1400 \text{ mA}$ Φ_V	Ordering Code	
LE T Q8WP-MBNB-34	224 450 lm	Q65111A8428	
LE T Q8WP-NANB-34	280 450 lm	Q65113A2445	



Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T _{op}	min.	-40 °C
	σp	max.	125 °C
Storage Temperature	T _{stg}	min.	-40 °C
	319	max.	125 °C
Junction Temperature	T _j	max.	150 °C
Forward Current	I _E	min.	40 mA
$T_S = 25 ^{\circ}C$,	max.	5000 mA
Forward Current pulsed	 F pulse		6000 mA
D = 0.5 ; f = 120 Hz; T _s = 25 °C	i puise		
ESD withstand voltage	V_{ESD}		2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	LOD		
Reverse current 2)	I _R	max.	200 mA



Characteristics

 I_F = 1400 mA; T_S = 25 °C

Parameter	Symbol		Values
Peak Wavelength	$\lambda_{\sf peak}$	typ.	520 nm
Dominant Wavelength 3)	λ_{dom}	min.	524 nm
	46	typ.	530 nm
		max.	536 nm
Spectral bandwidth at 50% I _{rel,max}	$\Delta \lambda$	typ.	30 nm
Viewing angle at 50% $\rm I_{_{ m V}}$	2φ	typ.	120 °
Radiating surface	A_{color}	typ.	1.5 x 1.2 mm²
Partial Flux acc. CIE 127:2007 $^{4)}$ I _F = 1400 mA	Ф _{Е/V, 120°}	typ.	0.82
Forward Voltage 5)	V_{F}	min.	2.20 V
$I_{\rm F} = 1400 \text{ mA}$		typ.	2.80 V
		max.	3.20 V
Reverse voltage (ESD device)	$V_{_{RESD}}$	min.	45 V
Reverse voltage ²⁾ I _R = 20 mA	V_R	max.	1.2 V
Real thermal resistance junction/solderpoint ⁶⁾	$R_{thJSreal}$	typ.	2.6 K / W
	and real	max.	3.6 K / W
Electrical thermal resistance junction/solderpoint 6)	R _{thJS elec.}	typ.	2.3 K / W
with efficiency η_e = 12 %		max.	3.2 K / W



Brightness Groups

Group	Luminous Flux ¹⁾ $I_F = 1400 \text{ mA}$ min. Φ_V	Luminous Flux ¹⁾ $I_F = 1400 \text{ mA}$ max. Φ_V	
MB	224 lm	280 lm	
NA	280 lm	355 lm	
NB	355 lm	450 lm	

Wavelength Groups

Group	Dominant Wavelength 3)	Dominant Wavelength 3)
	min.	max.
	$\lambda_{\sf dom}$	λ_{dom}
3	524 nm	530 nm
4	530 nm	536 nm

Group Name on Label

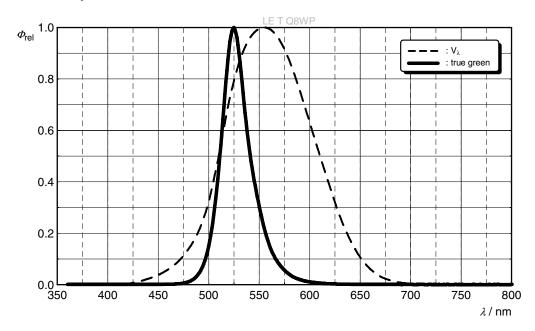
Example: MB-3

Brightness	Wavelength
MB	3



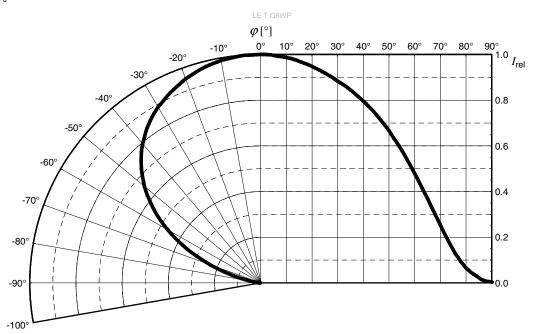
Relative Spectral Emission 4)

$$\Phi_{rel}$$
 = f (λ); I_F = 1400 mA; T_J = 25 °C



Radiation Characteristics 4)

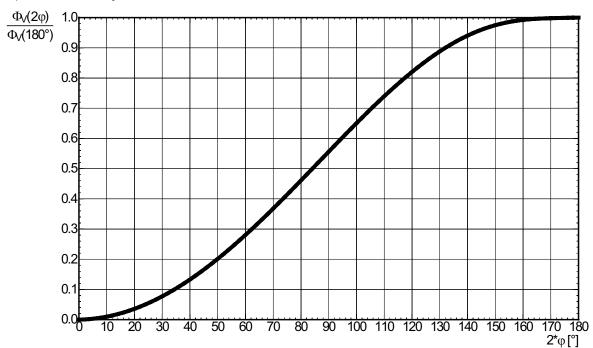
$$I_{rel} = f (\phi); T_J = 25 °C$$





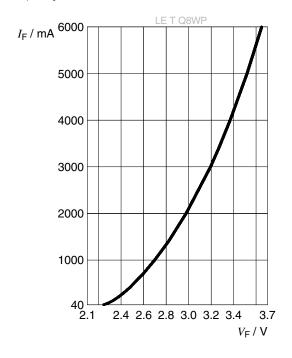
Relative Partial Flux 4)

 $\Phi_{_{V}}(2\phi)/\Phi_{_{V}}(180^{\circ}) = f(\phi); T_{_{J}} = 25 \, ^{\circ}C$



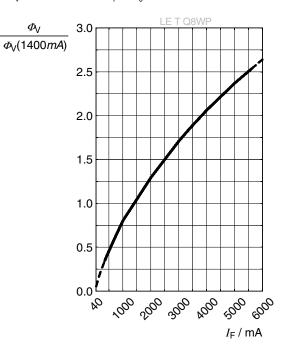
Forward current 4)

$$I_F = f(V_F); T_J = 25 °C$$



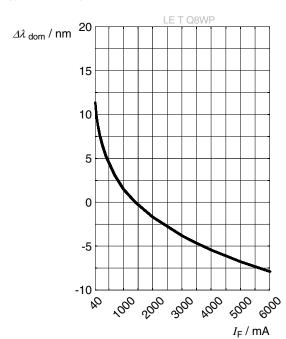
Relative Luminous Flux 4), 7)

$$\Phi_{V}/\Phi_{V}(1400 \text{ mA}) = f(I_{E}); T_{L} = 25 \text{ °C}$$



Dominant Wavelength 4)

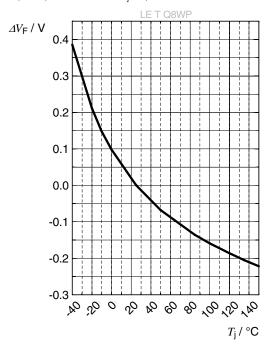
$$\Delta \lambda_{dom} = f(I_F); T_J = 25 \text{ }^{\circ}\text{C}$$





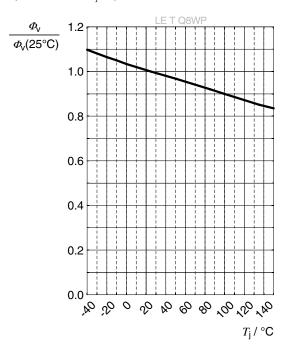
Forward Voltage 4)

$$\Delta V_F = V_F - V_F (25 \ ^{\circ}C) = f(T_j); I_F = 1400 \ mA$$



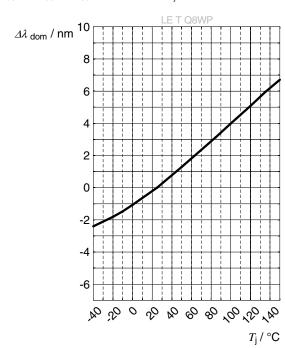
Relative Luminous Flux 4)

$$\Phi_{V}/\Phi_{V}(25 \text{ °C}) = f(T_{i}); I_{F} = 1400 \text{ mA}$$



Dominant Wavelength 4)

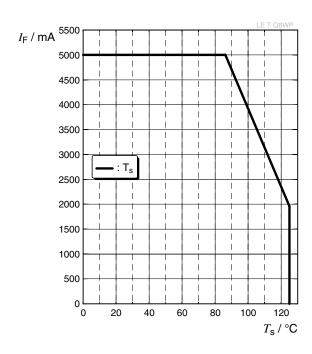
$$\Delta\lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}} (25 \text{ °C}) = f(T_j); I_F = 1400 \text{ mA}$$





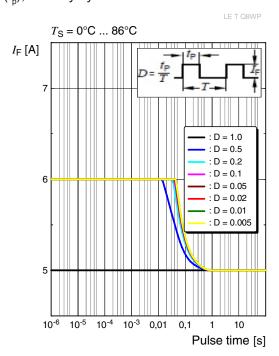
Max. Permissible Forward Current

 $I_{\scriptscriptstyle F} = f(T)$



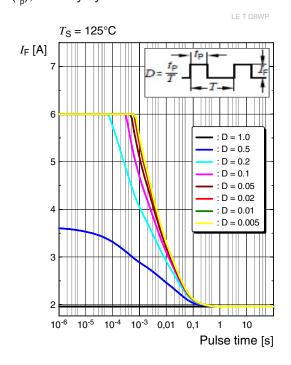
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; D: Duty cycle



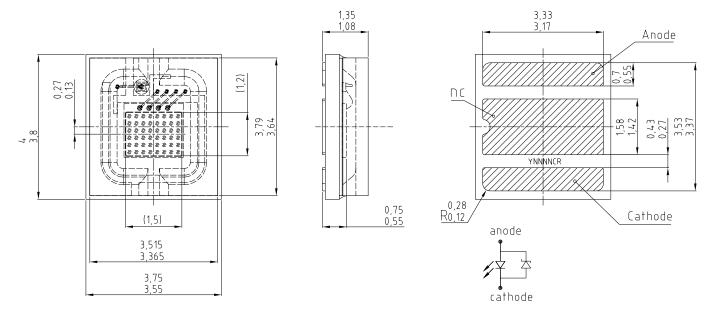
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; D: Duty cycle





Dimensional Drawing 8)



C63062-A4193-A2-04

Further Information:

Approximate Weight: 48.0 mg

Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

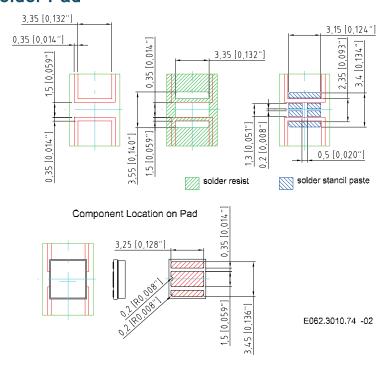
60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the

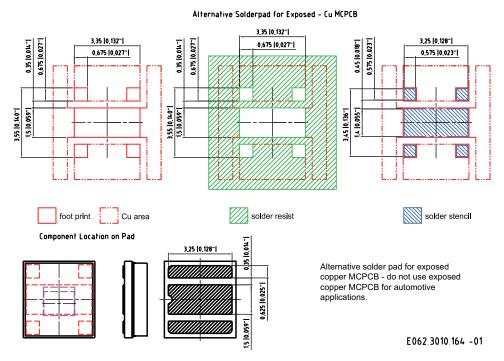
Chip.



Recommended Solder Pad 8)



Recommended Solder Pad 8)

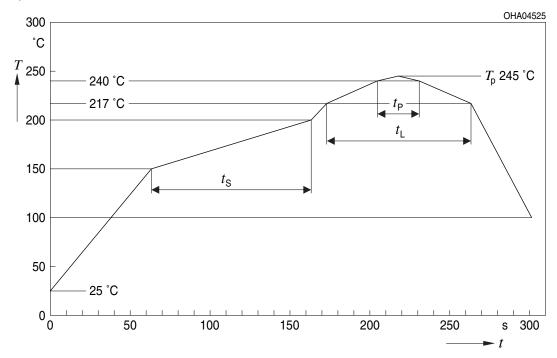


Exposed Copper MCPCB must not exceed thickness of 1mm. For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for any kind of wet cleaning or ultrasonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



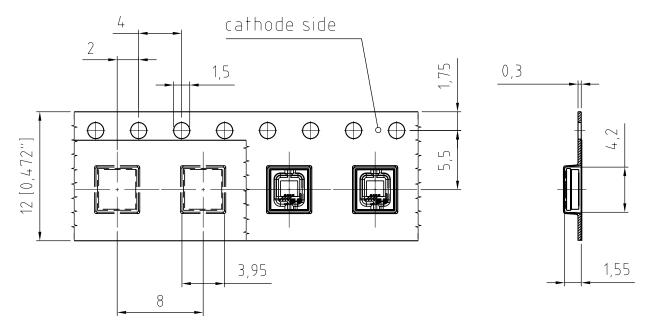
Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Assem			mbly Unit	
		Minimum	Recommendation	Maximum		
Ramp-up rate to preheat*)	'		2	3	K/s	
25 °C to 150 °C						
Time t _s	t _s	60	100	120	S	
T_{Smin} to T_{Smax}						
Ramp-up rate to peak*)			2	3	K/s	
T_{Smax} to T_{P}						
Liquidus temperature	T_{L}		217		°C	
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S	
Peak temperature	T _P		245	260	°C	
Time within 5 °C of the specified peak temperature T _p - 5 K	t _P	10	20	30	S	
Ramp-down rate* T _P to 100 °C			3	6	K/s	
Time 25 °C to T _P				480	S	

All temperatures refer to the center of the package, measured on the top of the component

^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



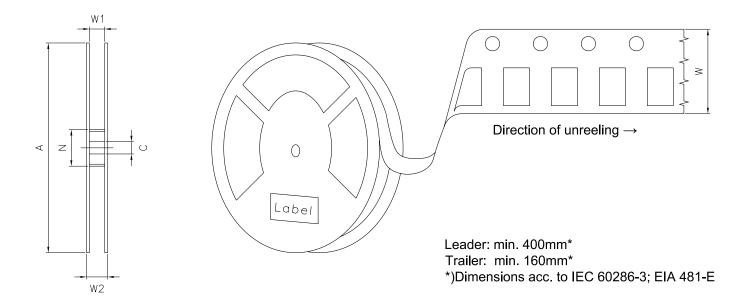
Taping 8)



C63062-A4193-B7 -04



Tape and Reel 9)



Reel Dimensions

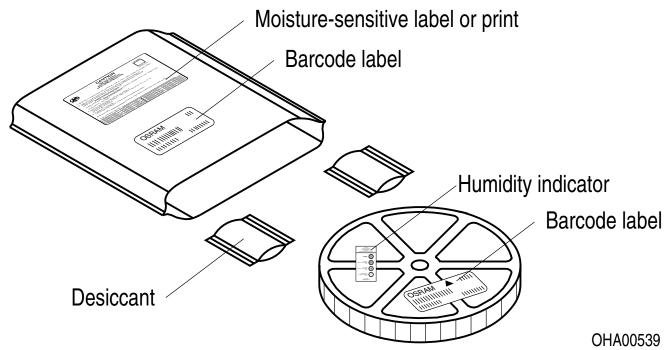
Α	W	N_{\min}	W_1	$W_{2 \text{max}}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	1000



Barcode-Product-Label (BPL)



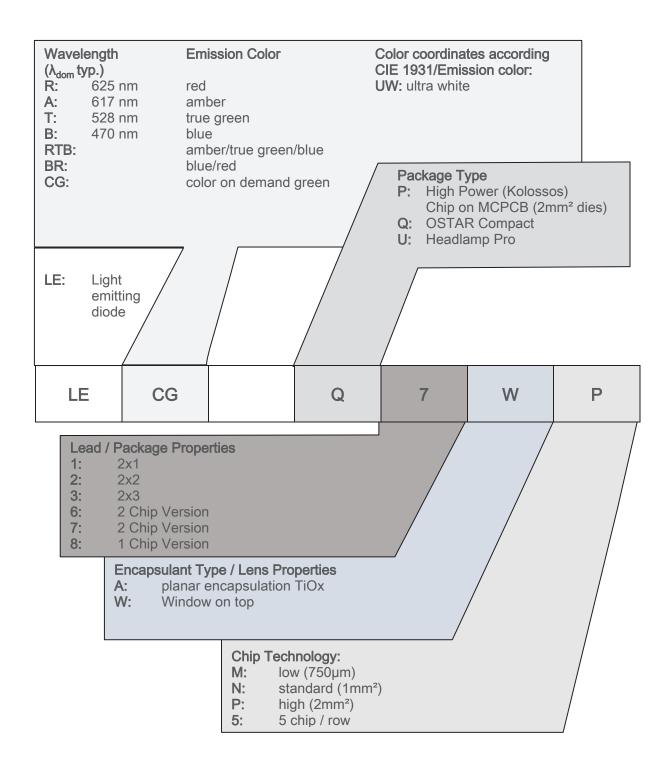
Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Type Designation System



LE T Q8WP **DATASHEET**



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class moderate risk (exposure time 0.25 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.



Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).
- Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k =
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 6) **Thermal Resistance:** Rth max is based on statistic values (6σ) .
- 7) Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- 9) Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

LE T Q8WP DATASHEET



Revision History

Version	Date	Change
1.3	2020-06-04	Schematic Transportation Box Dimensions of Transportation Box
1.4	2021-02-19	Ordering Information
1.5	2022-09-12	Characteristics Electro - Optical Characteristics (Diagrams) New Layout



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

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